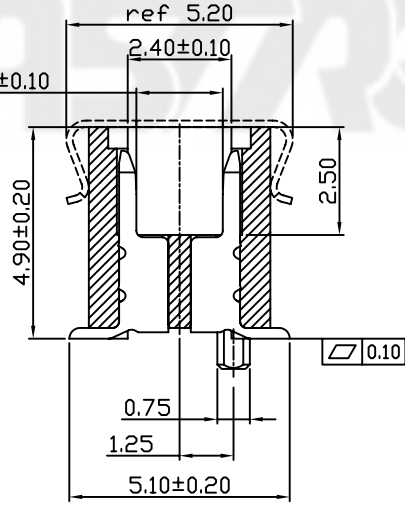
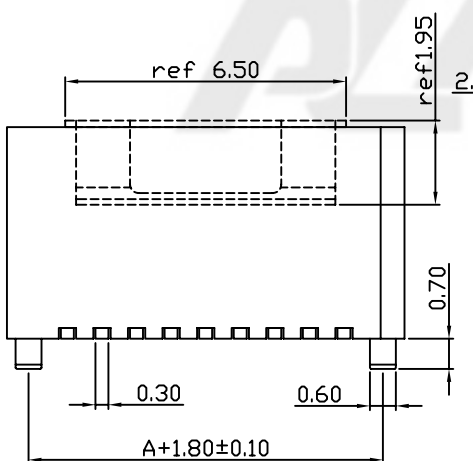
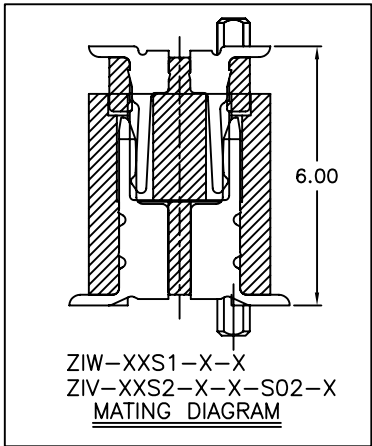
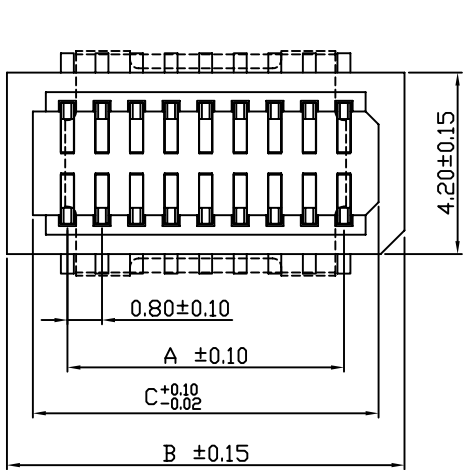


P/N	A	B	C
10	3.20	6.00	4.80
12	4.00	6.80	5.60
14	4.80	7.60	6.40
16	5.60	8.40	7.20
18	6.40	9.20	8.00
20	7.20	10.00	8.80
22	8.00	10.80	9.60
24	8.80	11.60	10.40
26	9.60	12.40	11.20
28	10.40	13.20	12.00
30	11.20	14.00	12.80
32	12.00	14.80	13.60
34	12.80	15.60	14.40
36	13.60	16.40	15.20
38	14.40	17.20	16.00
40	15.20	18.00	16.80
42	16.00	18.80	17.60
44	16.80	19.60	18.40
46	17.60	20.40	19.20
48	18.40	21.20	20.00
50	19.20	22.00	20.80
52	20.00	22.80	21.60
54	20.80	23.60	22.40
56	21.60	24.40	23.20
58	22.40	25.20	24.00
60	23.20	26.00	24.80
62	24.00	26.80	25.60
64	24.80	27.60	26.40
66	25.60	28.40	27.20
68	26.40	29.20	28.00
70	27.20	30.00	28.80
80	31.20	34.00	32.80
90	35.20	38.00	36.80
100	39.20	42.00	40.80



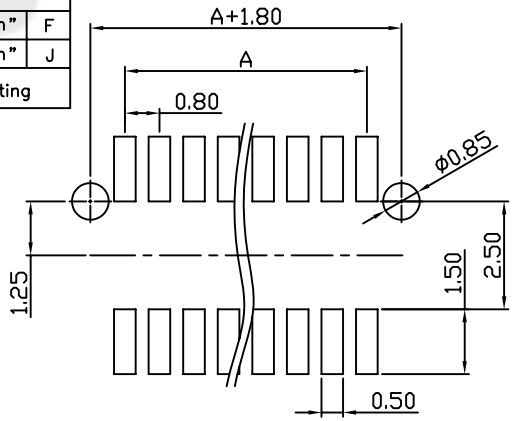
Rev.	ECN Number	Description	Drawn
10	EW07040025	----	Everard qi
11	CH11090079	增加包裝規範	XIHONG.LIU_08/01'11

NOTES: (UNLESS OTHERWISE SPECIFIED)

1. INSERTION FORCE: 150g MAX. PER CONTACT.
2. WITHDRAW FORCE: 25g MIN. PER CONTACT.
3. CONTACT RETENTION FORCE: 200g MIN. PER CONTACT.
4. CURRENT RATING: 0.5 AMPERE.
5. CONTACT RESISTANCE: 40 m ohms MAX. FOR INITIAL.
6. DIELECTRIC WITHSTANDING VOLTAGE: 500V AC rms. PER ONE MINUTE.
7. INSULATION RESISTANCE: 100 M ohms MIN..
8. HARMFUL MATERIAL SHOULD BE COMPLIANT TO DOC. "EI-0005" STANDARDS.
9. PRODUCT NUMBER MATRIX:

Definition	Code
◎ Tin plated	A
◎ Gold plated:	
flash	B 15m" F
10m"	E 30m" J
◎ lead free plating	

ZIV-XXS2-X-X-S02-\*  
P/N Plating  
NULL: TUBE(W/O MPAD)  
K: REEL  
C: Mylar +REEL  
B: MPAD+REEL  
E: MPAD+TUBE  
0: W/O Locating peg  
1: With Locating peg



RECOMMENED P.C.BOARD SMD LAYOUT  
(PCB TOLERANCE ±0.05)



GENERAL TOLERANCE	
XX. ±	XXX. ±
X. ± 0.30	.XXX ±
.X ± 0.25	X.* ± 3°
.XX ± 0.20	.X.* ± 2°

SCALE	N/A
UNIT	MM
SIZE	A4

ORIGINAL DRAWN	林秋蘭
CHECK	LANE SUN
APPROVE	POIL.WANG

DATE	05/05'11
DATE	08/01'11
DATE	08/01'11

DWG. NO.	600-0000-0303
PARTS NO.(INTENDED USE)	ZIV-XXS2-X-X-S02-*series

TITLE	CUSTOMER_DRAWING
-------	------------------

REV.	11
SHEET	1/3